

78SR100 Series**1.5 AMP POSITIVE STEP-DOWN
INTEGRATED SWITCHING REGULATOR**

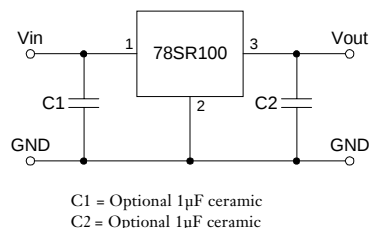
Revised 6/30/98



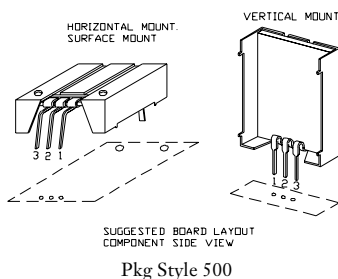
- Very Small Footprint
- High Efficiency > 85%
- Self-Contained Inductor
- Internal Short-Circuit Protection
- Over-Temperature Protection
- Wide Input Range

The 78SR100 is a series of wide input voltage, 3-terminal Integrated Switching Regulators (ISRs). These ISRs have a maximum output current of 1.5A and an output voltage that is laser trimmed to a variety of industry standard voltages.

These 78 series regulators have excellent line and load regulation with internal short-circuit and over-temperature protection, are very flexible, and may be used in a wide variety of applications.

Standard Application**Pin-Out Information**

Pin	Function
1	V _{in}
2	GND
3	V _{out}

**Ordering Information****78SR1 XX Y C****Output Voltage**

05 = 5.0 Volts
53 = 5.25 Volts
06 = 6.0 Volts
74 = 7.15 Volts
08 = 8.0 Volts
09 = 9.0 Volts
10 = 10.0 Volts
12 = 12.0 Volts
14 = 13.9 Volts
15 = 15.0 Volts

Package Suffix

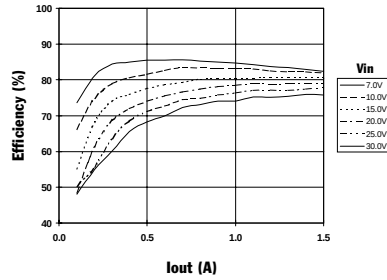
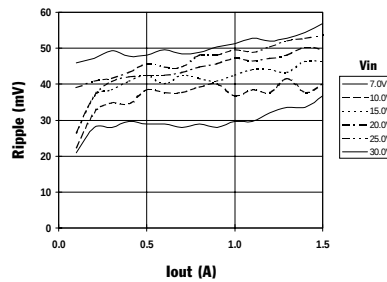
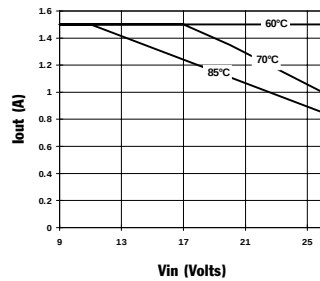
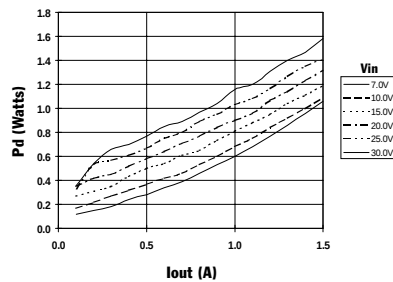
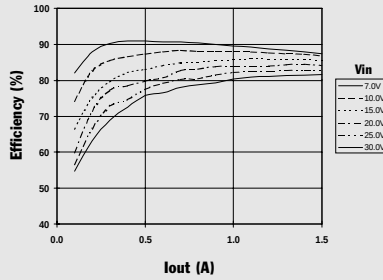
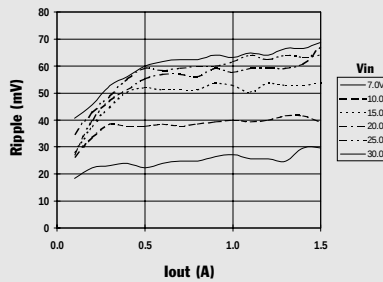
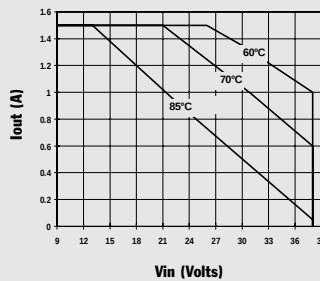
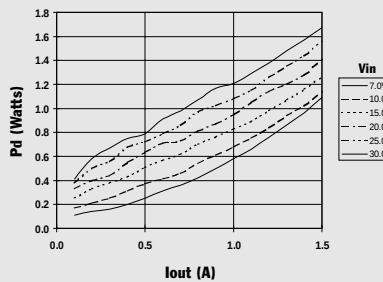
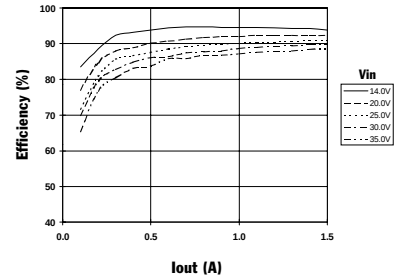
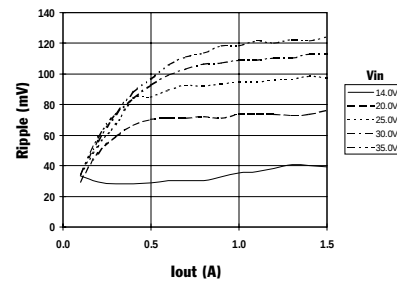
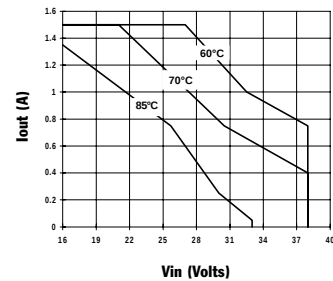
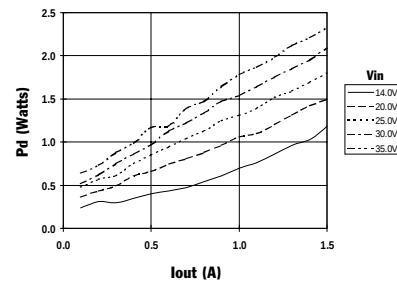
V = Vertical Mount
S = Surface Mount
H = Horizontal Mount

Specifications

Characteristics (T _a = 25°C unless noted)	Symbols	Conditions	78SR100 SERIES			
			Min	Typ	Max	Units
Output Current	I _O	Over V _{in} range	0.1*	—	1.5	A
Short Circuit Current	I _{sc}	V _{in} = V _{in} min	—	3.5	—	A _{pk}
Input Voltage Range	V _{in}	0.1 ≤ I _O ≤ 1.5A V _o = 5V V _o = 12V	7 14.5	—	30 30	V
Output Voltage Tolerance	ΔV _o	Over V _{in} range, I _O = 1.5A T _a = 0°C to +60°C	—	±1.0	±2.0	%V _O
Line Regulation	Reg _{line}	Over V _{in} range	—	±0.2	±0.4	%V _O
Load Regulation	Reg _{load}	0.1 ≤ I _O ≤ 1.5A	—	±0.1	±0.2	%V _O
V _o Ripple/Noise	V _n	V _{in} = 9V, I _O = 1.5A V _{in} = 16V, I _O = 1.5A V _o = 5V V _o = 12V	—	50 80	—	mV _{pp} mV _{pp}
Transient Response	t _{tr}	50% load change V _o over/undershoot	— —	100 30	—	µSec %V _O
Efficiency	η	V _{in} = 10V, I _O = 1A V _{in} = 17V, I _O = 1A V _o = 5V V _o = 12V	— —	85 90	—	% %
Switching Frequency	f _o	Over V _{in} range, I _O = 1.5A	600	650	700	kHz
Absolute Maximum Operating Temperature Range	T _a	—	-40	—	+85	°C
Recommended Operating Temperature Range	T _a	Free Air Convection, (40-60LFM) At V _{in} = 24V, I _O = 1.0A	-40	—	+80**	°C
Thermal Resistance	θ _{ja}	Free Air Convection, (40-60LFM)	—	45	—	°C/W
Storage Temperature	T _s	—	-40	—	+125	°C
Mechanical Shock	—	Per Mil-STD-883D, Method 2002.3	—	500	—	G's
Mechanical Vibration	—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	—	5	—	G's
Weight	—	—	—	6.5	—	grams

*ISR will operate down to no load with reduced specifications.

**See Thermal Derating chart.

78SR100 Series**CHARACTERISTIC DATA****78SR133 3.3 VDC** (See Note 1)**Efficiency vs Output Current****Ripple vs Output Current****Thermal Derating (Ta)** (See Note 2)**Power Dissipation vs Output Current****78SR105 5.0 VDC** (See Note 1)**Efficiency vs Output Current****Ripple vs Output Current****Thermal Derating (Ta)** (See Note 2)**Power Dissipation vs Output Current****78SR112 12.0 VDC** (See Note 1)**Efficiency vs Output Current****Ripple vs Output Current****Thermal Derating (Ta)** (See Note 2)**Power Dissipation vs Output Current**

Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR.

Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM. (See Thermal Application Notes.)

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
78SR105SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR106SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR108SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR109SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR109SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR110VC	OBSOLETE	SIP MODULE	EFD	3		TBD	Call TI	Call TI	-40 to 85		
78SR112SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR114WC	OBSOLETE	SIP MODULE	EFW	3		TBD	Call TI	Call TI	-40 to 85		
78SR115SC	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR115SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR153SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		
78SR153TC	OBSOLETE	SIP MODULE	EFT	3		TBD	Call TI	Call TI	-40 to 85		
78SR174SCT	OBSOLETE	SIP MODULE	EFC	3		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- ⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- ⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- ⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- ⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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